

DECLARATION FOR PATENT APPLICATION (JOINT OR SOLE)

(Under 37 CFR § 1.63; with Power of Attorney)

FROMMER LAWRENCE & HAUG LLP

FLH File No. 450134-04839

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention ENTITLED:

HEAT DISSIPATING STRUCTURE FOR AN ELECTRONIC DEVICE

the specification of which

X is attached hereto.

_____ was filed on _____ as Application Serial No. _____,

with amendment(s) through _____ (if applicable, give dates).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, Sec. 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s) [list additional applications on separate page]: **Priority Claimed:**

<u>Number:</u>	<u>Country:</u>	<u>Filed (Day/Month/Year):</u>	<u>Yes</u>	<u>No</u>
2002-296897	Japan	10 October 2002	X	

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code § 112, I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, Sec. 1.56, which became available between the filing date of the prior application and the national or PCT international filing date of this application:

Prior U.S. Application(s) [list additional applications on separate page]:

<u>Appln. Ser. Number:</u>	<u>Filed (Day/Month/Year):</u>	<u>Status (patented, pending, abandoned):</u>
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I hereby appoint WILLIAM S. FROMMER, Registration No. 25,506, DENNIS M. SMID, Registration No. 34,930 and HANS R. MAHR, Registration No. 46,138 or their duly appointed associate, my attorneys, with full power of substitution and revocation, to prosecute this application, to make alterations and amendments therein, to file continuation and divisional applications thereof, to receive the Patent, and to transact all business in the Patent and Trademark Office and in the Courts in connection therewith, and specify that all communications about the application are to be directed to the following correspondence address:

WILLIAM S. FROMMER, Esq.
c/o FROMMER LAWRENCE & HAUG LLP
745 Fifth Avenue
New York, New York 10151

Direct all telephone calls to:
(212) 588-0800
to the attention of:
WILLIAM S. FROMMER

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

INVENTOR(S):

Signature: _____ Date: _____

Full name of sole or first inventor: Kazuaki YAZAWA
Residence: Tokyo, Japan
Citizenship: Japan

Signature: _____ Date: _____

Full name of 2nd joint inventor (if any): _____
Residence: _____
Citizenship: _____

Signature: _____ Date: _____

Full name of 3rd joint inventor (if any): _____
Residence: _____
Citizenship: _____

[Similarly list additional inventors on separate page]

Post Office Address(es) of inventor(s):

[if all inventors have the same post office address]

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Tokyo 107-0062, JAPAN

Note: A post office address must be provided for each inventor.